

TO-220-2 Silicon Carbide Schottky Diode

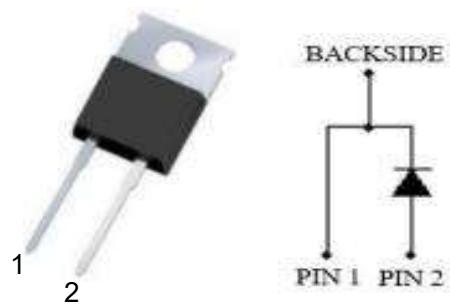
SiC Diode 650 V, 6 A, 25nC

General Description

This product family offers state of the art performance. It is designed for high frequency applications where high efficiency and high reliability are required.

Features

- Zero Forward/Reverse Recovery Current
- High Blocking Voltage
- High Frequency Operation
- Positive Temperature Coefficient on VF
- Temperature Independent Switching Behavior



Applications

- Motor Drives
- Solar
- AC/DC converters
- DC/DC converters
- Uninterruptable power supplies

TO-220-2 Pin definition

Benefits

- Higher System Efficiency
- Parallel Device Convenience without thermal runaway
- Higher Temperature Application
- No Switching loss
- Hard Switching & Higher Reliability
- Environmental Protection

Key performance parameters

Type	V_R	I_F $T_C=150^\circ C$	Q_C
KWSC65C6T2	650 V	6A	25 nC

Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures.

Typical Characteristics

Maximum Ratings

$T_C=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	650	V
Peak Reverse Surge Voltage	V_{RSM}	650	V
DC Blocking Voltage	V_R	650	V

Maximum Ratings

$T_C=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Test conditions	Value	Unit
V_{RRM}	Repetitive peak reverse voltage		650	V
I_F	Continuous forward current	$T_C=25^\circ\text{C}$ $T_C=160^\circ\text{C}$	26 6	A
I_{FSM}	Non-Repetitive forward surge current	$T_C=25^\circ\text{C}$, $t_p=10\text{ms}$, Half Sine Wave	60	A
$\int i^2 dt$	$i^2 t$ value	$T_c=25^\circ\text{C}$, $t_p=10\text{ms}$	18	A^2s
P_{tot}	Power dissipation	$T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$	103 44	W
T_j	Operating junction temperature		-55~175	$^\circ\text{C}$
T_{stg}	Storage temperature		-55~175	$^\circ\text{C}$

Thermal Resistance

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(jc)}$	Thermal Resistance from Junction to Cas		1.45		$^\circ\text{C/W}$



Typical Characteristics

Electrical Characteristic

$T_C = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
V_{DC}	DC blocking voltage	$T_j=25^\circ\text{C}$	650			V
V_F	Diode forward voltage	$I_F=6\text{A}, T_j=25^\circ\text{C}$ $I_F=6\text{A}, T_j=135^\circ\text{C}$ $I_F=6\text{A}, T_j=175^\circ\text{C}$		1.25 1.32 1.38	1.48 1.74 1.90	V
I_R	Reverse current	$V_R=650\text{V}, T_j=25^\circ\text{C}$ $V_R=650\text{V}, T_j=175^\circ\text{C}$		0.5 15	50 200	μA

AC Characteristic

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
Q_C	Total capacitive charge	$V_R=400\text{V}, T_j=25^\circ\text{C}$ $Q_C = \int_0^V R_C(V)dV$		25		nC
C	Total capacitance	$V_R=1\text{V} f=1\text{MHz}$ $V_R=300\text{V} f=1\text{MHz}$ $V_R=600\text{V} f=1\text{MHz}$		350 42 36		pF
E_C	Capacitance stored energy	$V_R=400\text{V}$		3.8		μJ

Typical Characteristics

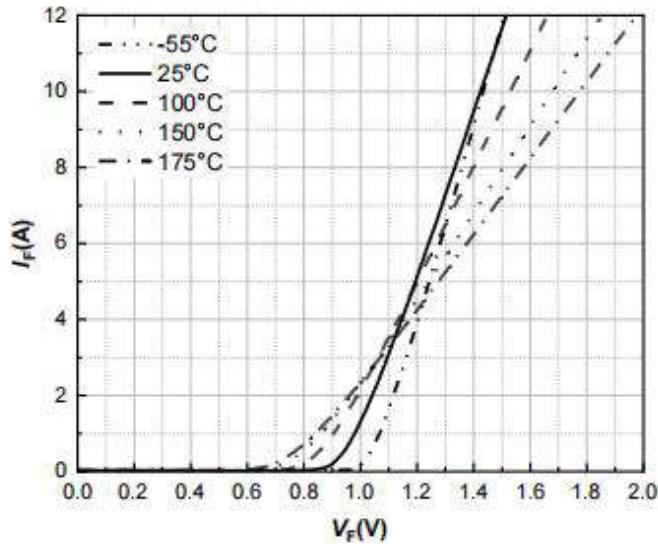


Figure 1. Typical forward characteristics

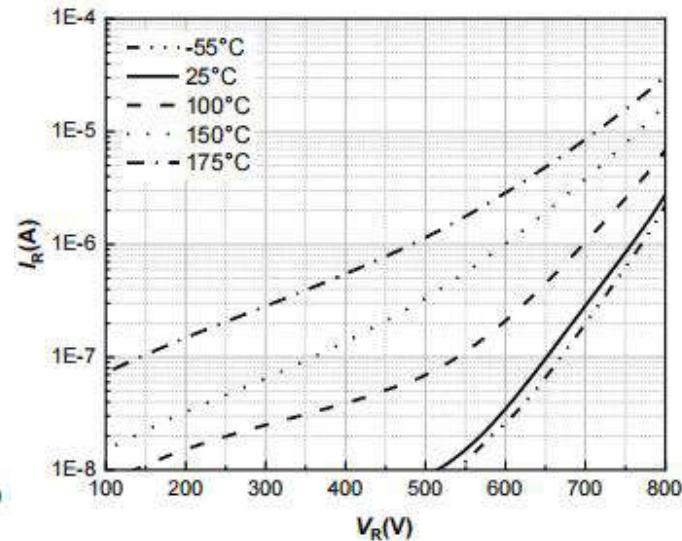


Figure 2. Typical reverse current as function of reverse voltage

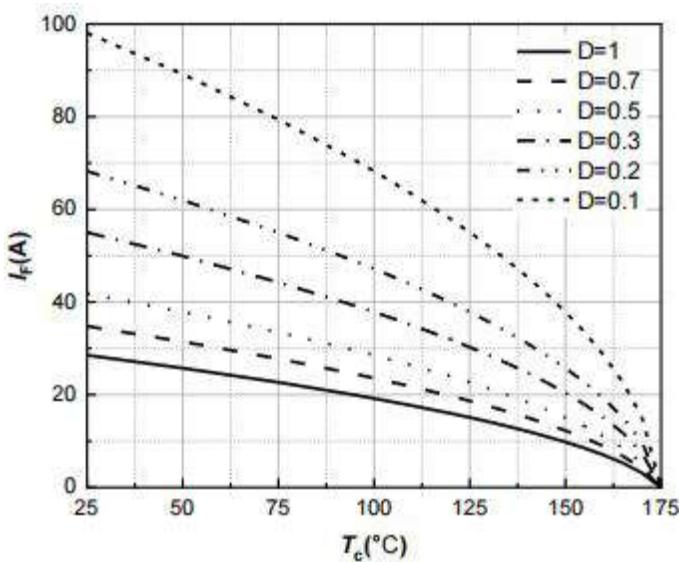


Figure 3. Diode forward current as function of temperature, D=duty cycle

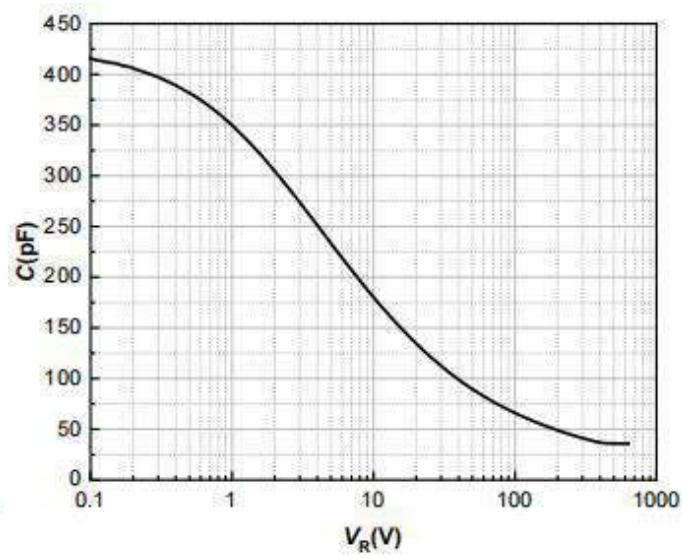


Figure 4. Typical capacitance as function of reverse voltage, $C=f(V_R)$; $T_j=25^\circ\text{C}$; $f=1\text{ MHz}$

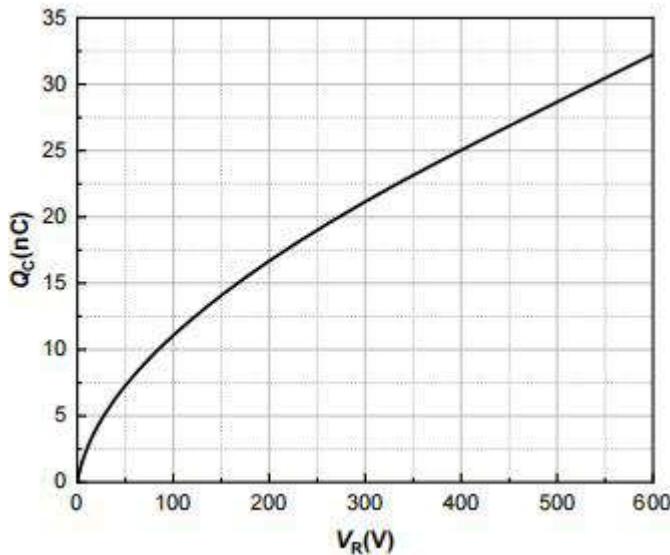


Figure 5. Typical reverse charge as function of reverse voltage

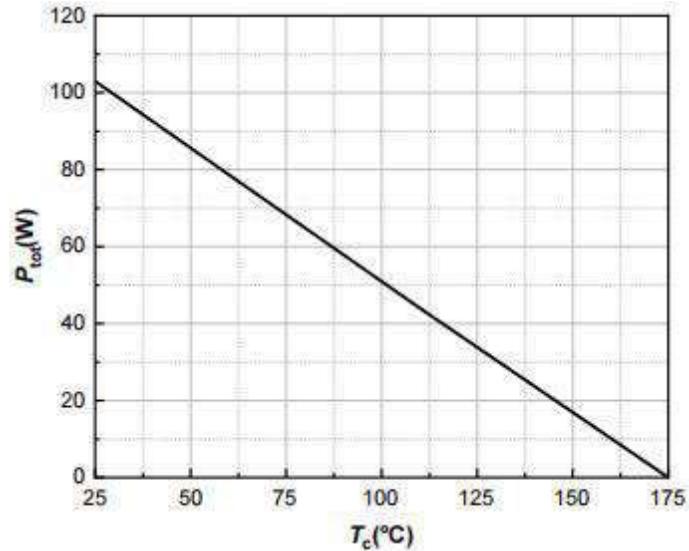


Figure 6. Power dissipation as function of case temperature

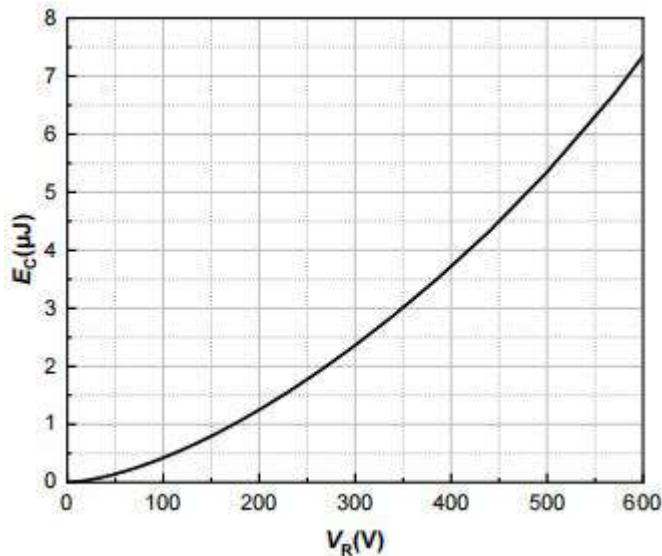


Figure 7. Capacitance stored energy

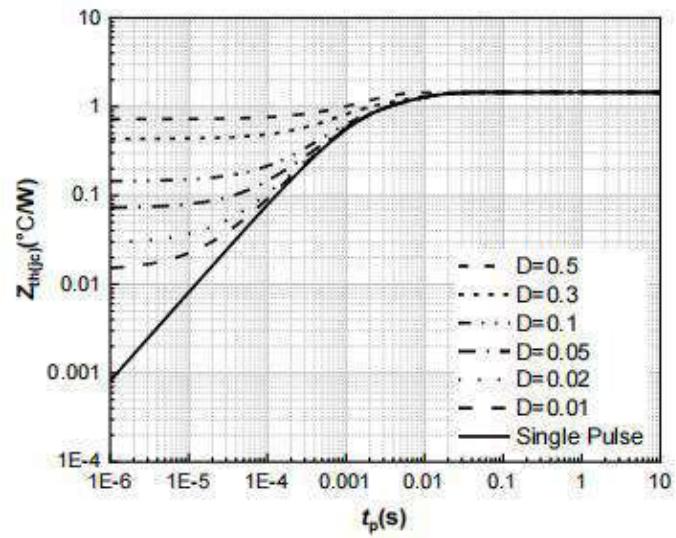
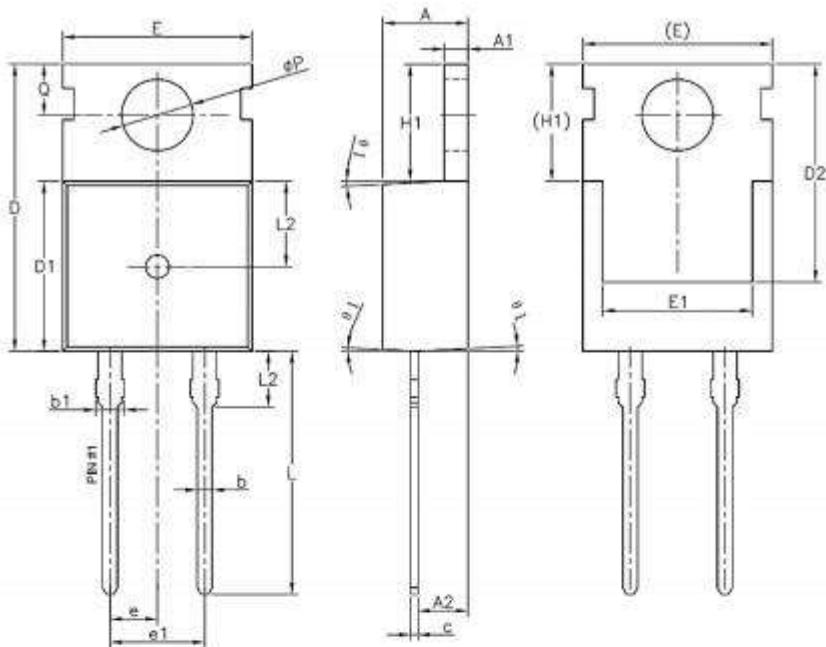


Figure 8. Max.transient thermal impedance, $Z_{th(jc)} = f(t_p)$, parameter: $D = t_p/T$

Package Outline Dimensions

Package Outline: TO-220-2



SYMBOL	Unit: mm		
	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	-	0.90
b1	1.42	-	1.57
c	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	-	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54 BSC		
e1	5.08 BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	-	-	3.50
L2	4.60 REF		
ΦP	3.55	3.60	3.65
Q	2.73	-	2.87
θ1	1°	3°	5°